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Global Wafer Surface Thinning Machine Market 2025 by Manufacturers, Regions, Type and Application, Forecast to 2031

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Abstracts

According to our (Global Info Research) latest study, the global Wafer Surface Thinning Machine market size was valued at US$ 1072 million in 2024 and is forecast to a readjusted size of USD 1732 million by 2031 with a CAGR of 6.9% during review period.

Wafer Surface Thinning Machine uses a centrally located robot to move a wafer from an input station to a measuring station. Thereafter, the wafer is moved into a grind station and a wash station sequentially. The robot is able to move a wafer from the wash station to either the measuring station for after-grinding measurements or directly to an output station. During grinding of one wafer, a second wafer may be held between the measuring station and the grind station while a ground wafer is moved from the wash station to the measuring station for after-grinding measurements

The Wafer Surface Thinning Machines market, primarily driven by the increasing demand for precision and efficiency in semiconductor manufacturing, is growing rapidly across the globe. Wafer Surface Thinning Machines are integral in wafer thinning processes, where the primary applications include the processing of 200mm and 300mm wafers. Among the various types of Wafer Surface Thinning Machines, the fully automatic Wafer Surface Thinning Machines dominate the market, they have higher automation levels, allowing for increased efficiency and precision, accounting for approximately 52% of the global market share. The most significant application market is for 300mm wafers, which accounts for 83% of the global demand, primarily driven by the advanced semiconductor manufacturing processes that require thinner wafers with high precision. Geographically, the Asia-Pacific (APAC) region holds the largest consumption share, accounting for about 78% of the global market, driven by the robust semiconductor manufacturing ecosystem in countries like China, Japan, South Korea,

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and Taiwan.

Manufacturers, like Disco, TOKYO SEIMITSU, Okamoto Semiconductor Equipment Division, CETC, G&N, etc. are well-known for the wonderful performance of their Wafer Surface Thinning Machine and related services. The top five players account for about 90% of the revenue market in 2024.

Market Drivers:

Technological Advancements in Semiconductor Manufacturing: As the demand for smaller, more powerful, and energy-efficient electronic devices grows, semiconductor manufacturers are continuously advancing their processes to meet these demands. This includes the need for thinner, more precisely engineered wafers, driving the demand for high-performance Wafer Surface Thinning Machines. Fully automatic Wafer Surface Thinning Machines, known for their precision and ability to handle larger volumes, are particularly in demand to meet these stringent manufacturing requirements.

Miniaturization of Electronic Devices: The global trend towards smaller, more compact electronic devices—such as smartphones, wearables, and IoT devices—requires thinner semiconductor wafers. As a result, there is a growing demand for wafer thinning solutions that can maintain high quality while reducing thickness. Fully automatic Wafer Surface Thinning Machines are the preferred solution, as they offer high precision and productivity.

Surge in Semiconductor Demand: The semiconductor industry is experiencing significant growth, driven by the rise in demand for various electronic applications, including computing, communication, and automotive systems. As the industry's focus shifts towards advanced technology nodes, the demand for larger wafers, particularly 300mm wafers, is growing. These trends are contributing to the expansion of the Wafer Surface Thinning Machine market, especially in regions such as APAC, which dominate semiconductor manufacturing.

Growth in 300mm Wafer Demand: The 300mm wafer segment is the most significant application for Wafer Surface Thinning Machines, accounting for 83% of the global market share. Larger wafers allow for more chips to be processed at once, reducing manufacturing costs per chip. This increase in 300mm wafer production is a significant growth factor for the Wafer Surface Thinning Machine market, as manufacturers need specialized equipment to handle the larger wafers efficiently.

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Shift Towards Fully Automated Solutions: Fully automated Wafer Surface Thinning Machines are gaining popularity due to their higher efficiency, reduced labor costs, and the ability to maintain consistency across large batches. As semiconductor manufacturers continue to scale production, automation becomes increasingly essential to meet high-volume production requirements without compromising quality.

Conclusion:

The Wafer Surface Thinning Machine market is poised for significant growth, driven by advancements in semiconductor manufacturing, the increasing demand for thinner and more precise wafers, and the rise in 300mm wafer processing. Fully automatic Wafer Surface Thinning Machines, which dominate the market with a 52% share, will continue to lead the market due to their higher efficiency and precision.

The APAC region remains the largest consumer of Wafer Surface Thinning Machines, accounting for 78% of the global market. However, despite these strong growth drivers, challenges such as high initial investment costs and technological complexity may pose barriers to market entry for smaller players. Manufacturers will need to innovate and focus on automation, precision, and cost-effective solutions to capitalize on the growing demand for Wafer Surface Thinning Machine.

This report is a detailed and comprehensive analysis for global Wafer Surface Thinning Machine market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Wafer Surface Thinning Machine market size and forecasts, in consumption value ($ Million), sales quantity (Units), and average selling prices (K US$/Unit), 2020-2031

Global Wafer Surface Thinning Machine market size and forecasts by region and country, in consumption value ($ Million), sales quantity (Units), and average selling prices (K US$/Unit), 2020-2031

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Global Wafer Surface Thinning Machine market size and forecasts, by Type and by Application, in consumption value ($ Million), sales quantity (Units), and average selling prices (K US$/Unit), 2020-2031

Global Wafer Surface Thinning Machine market shares of main players, shipments in revenue ($ Million), sales quantity (Units), and ASP (K US$/Unit), 2020-2025

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries
To assess the growth potential for Wafer Surface Thinning Machine
To forecast future growth in each product and end-use market
To assess competitive factors affecting the marketplace

This report profiles key players in the global Wafer Surface Thinning Machine market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Disco, TOKYO SEIMITSU, G&N, Okamoto Semiconductor Equipment Division, CETC, Koyo Machinery, Revasum, WAIDA MFG, Hunan Yujing Machine Industrial, SpeedFam, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Wafer Surface Thinning Machine market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

Fully Automatic Wafer Grinders

Semi-Automatic Wafer Grinders

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Market segment by Application

Silicon Wafer

Compound Semiconductors

Major players covered

Disco

TOKYO SEIMITSU

G&N

Okamoto Semiconductor Equipment Division

CETC

Koyo Machinery

Revasum

WAIDA MFG

Hunan Yujing Machine Industrial

SpeedFam

TSD

Engis Corporation

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)
Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)
Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

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South America (Brazil, Argentina, Colombia, and Rest of South America)
Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Wafer Surface Thinning Machine product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Wafer Surface Thinning Machine, with price, sales quantity, revenue, and global market share of Wafer Surface Thinning Machine from 2020 to 2025.

Chapter 3, the Wafer Surface Thinning Machine competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Wafer Surface Thinning Machine breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2020 to 2031.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2020 to 2031.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2020 to 2025.and Wafer Surface Thinning Machine market forecast, by regions, by Type, and by Application, with sales and revenue, from 2026 to 2031.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Wafer Surface Thinning Machine.

Chapter 14 and 15, to describe Wafer Surface Thinning Machine sales channel, distributors, customers, research findings and conclusion.

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